

Sensors and Materials

Special Issue on International Conference on BioSensors, BioElectronics, BioMedical Devices, BioMEMS/NEMS and Applications 2019 (Bio4Apps 2019)

Call for Papers

This special issue of *Sensors and Materials* aims to focus on bioelectronics, biosensors, biomedical devices, Bio-MEMS/NEMS and Sensing Biology with a strong emphasis on commercialization and applications. All articles related to these technology and applications are welcome.

Scope:

- Bio Sensors
 - Lab-on-chip
 - Miniaturized diagnostic
 - Novel bioelectric sensing
 - Nanophotonics/THz Sensing
 - Physiological monitoring
- Bio Electronics
 - Biomedical signal processing
 - Body area sensor networks
 - Circuits for biomedical applications/ devices
 - Flexible electronics
 - Implantable electronics
- BioMedical devices
 - Bio-imaging technology
 - Bio-compatible materials and packaging
 - Implantable medical devices
 - Prosthesis and Neural probes
 - Surgical robots
- BioMEMS/NEMS
 - Drug delivery
 - Energy harvesting technology
 - MEMS/NEMS for biomedical applications
 - Microfluidics for biomedical applications

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Journal website: <https://myukk.org/>

Guest Editors: Prof. Masaya Miyazaki (Kyushu University)
and Assistant. Prof. Hirofumi Nogami (Kyushu University)

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If you have any questions, please feel free to contact the editorial staff at the address below.

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